L Number	Hits	Search Text	DB	Time stamp
1	2458398	chip die dice ic (integrated adj circuit) semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 08:50
2	253072	(plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 10:58
3	18493	wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 08:54
4	831653	control and memory znc (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 08:55
5	2561	control and memory and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 10:53
6	1597	(lead leadframe (lead adj frame)) and (control and memory and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 10:51
7	1466	((lead leadframe (lead adj frame)) and (control and memory and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))))) and (pad terminal electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 10:52
8	10507	(lead leadframe (lead adj frame)) and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 10:52
9	9142	((lead leadframe (lead adj frame)) and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor)))) and (pad terminal electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 10:52
10	7676	(((lead leadframe (lead adj frame)) and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor)))) and (pad terminal electrode)) not (((lead leadframe (lead adj frame)) and (control and memory and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))))) and (pad terminal electrode))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 10:52

11	3254	(control memory nonvolatile (non adj volatile)) and ((((lead leadframe (lead adj frame)) and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))))) and (pad terminal electrode)) not (((lead leadframe (lead adj frame)) and (control and memory and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))))) and (pad terminal electrode)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 10:57
12	1090	(stack stacked stacking) and ((control memory nonvolatile (non adj volatile)) and ((((lead leadframe (lead adj frame)) and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))))) and (pad terminal electrode)) not (((lead leadframe (lead adj frame)) and (control and memory and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))))) and (pad terminal electrode))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 10:59

L Number	Hits	Search Text	DB	Time stamp
1	2458398	chip die dice ic (integrated adj circuit) semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 08:50
2	253072	(plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 08:52
3	18493	wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 08:54
4	831653	control and memory znc (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 08:55
5	2561	control and memory and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 08:55
6	1597	(lead leadframe (lead adj frame)) and (control and memory and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 08:56
7	1466	((lead leadframe (lead adj frame)) and (control and memory and (wire same ((plurality stack stacked stacking multi multiple) with (chip die dice ic (integrated adj circuit) semiconductor))))) and (pad terminal electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/04 08:57